

RELIABILITY REPORT  
FOR  
MAX17015AETP+  
(MAX17005A, MA17006A, MAX170015A)  
PLASTIC ENCAPSULATED DEVICES

March 15, 2009

**MAXIM INTEGRATED PRODUCTS**

120 SAN GABRIEL DR.  
SUNNYVALE, CA 94086

<b>Approved by</b>
Ken Wendel
Quality Assurance
Director, Reliability Engineering

## Conclusion

The MAX17015AETP+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

## Table of Contents

<b>I. ....Device Description</b>	<b>V. ....Quality Assurance Information</b>
<b>II. ....Manufacturing Information</b>	<b>VI. ....Reliability Evaluation</b>
<b>III. ....Packaging Information</b>	<b>IV. ....Die Information</b>
<b>.....Attachments</b>	

### I. Device Description

#### A. General

The MAX17005A/MAX17006A/MAX17015A are high-frequency multichemistry battery chargers. These circuits feature a new high-frequency current-mode architecture that significantly reduces component size and cost\*. The charger uses a high-side MOSFET with n-channel synchronous rectifier. Widely adjustable charge current, charge voltage, and input current limit simplify the construction of highly accurate and efficient chargers. The charge voltage and charge current are set with analog control inputs. The charge current setting can also be adjusted with a PWM input. High-accuracy current-sense amplifiers provide fast cycle-by-cycle current-mode control to protect against short circuits to the battery and respond quickly to system load transients. In addition, the charger provides a high-accuracy analog output that is proportional to the adapter current. In the MAX17015A, this current monitor remains active when the adapter is absent to monitor battery discharge current. The MAX17005A charges three or four Li+ series cells, and the MAX17006A charges two or three Li+ series cells. The MAX17015A adjusts the charge voltage setting and the number of cells through a feedback resistor-divider from the output. All variants of the charger can provide at least 4A of charge current with a 10m sense resistor. The charger utilizes a charge pump to control an n-channel adapter selection switch. The charge pump remains active even when the charger is off. When the adapter is absent, a p-channel MOSFET selects the battery. The MAX17005A/MAX17006A/MAX17015A are available in a small, 4mm x 4mm x 0.8mm 20-pin, lead-free TQFN package. An evaluation kit is available to reduce design time.

## II. Manufacturing Information

A. Description/Function:	1.2MHz Low-Cost, High-Performance Chargers
B. Process:	S4
C. Number of Device Transistors:	12990
D. Fabrication Location:	Japan
E. Assembly Location:	ASAT China, UTL Thailand
F. Date of Initial Production:	October 25, 2008

## III. Packaging Information

A. Package Type:	20-pin TQFN 4x4
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Au (1.0 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	59°C/W
K. Single Layer Theta Jc:	5.7°C/W
L. Multi Layer Theta Ja:	39°C/W
M. Multi Layer Theta Jc:	5.7°C/W

## IV. Die Information

A. Dimensions:	78 X 88 mils
B. Passivation:	Si <sub>3</sub> N <sub>4</sub> /SiO <sub>2</sub> (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Aluminum/Si (Si = 1%)
D. Backside Metallization:	None
E. Minimum Metal Width:	Metal1 = 0.5 / Metal2 = 0.6 / Metal3 = 0.6 microns (as drawn)
F. Minimum Metal Spacing:	Metal1 = 0.45 / Metal2 = 0.5 / Metal3 = 0.6 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO <sub>2</sub>
I. Die Separation Method:	Wafer Saw

## V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

## VI. Reliability Evaluation

### A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 48 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 22.4 \times 10^{-9}$$

$$\lambda = 22.4 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at <http://www.maxim-ic.com/>. Current monitor data for the S4 Process results in a FIT Rate of 0.75 @ 25C and 13.0 @ 55C (0.8 eV, 60% UCL)

### B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

### C. E.S.D. and Latch-Up Testing

The PD97-2 die type has been found to have all pins able to withstand a HBM transient pulse of +/-1000 V per JEDEC JESD22-A114-D. Latch-Up testing has shown that this device withstands a current of +/-100 mA, 1.5x VCCMax per JESD 78.

**Table 1**  
Reliability Evaluation Test Results

**MAX17015AETP+**

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
<b>Static Life Test</b> (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	48	0
<b>Moisture Testing</b> (Note 2) 85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
<b>Mechanical Stress</b> (Note 2) Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data